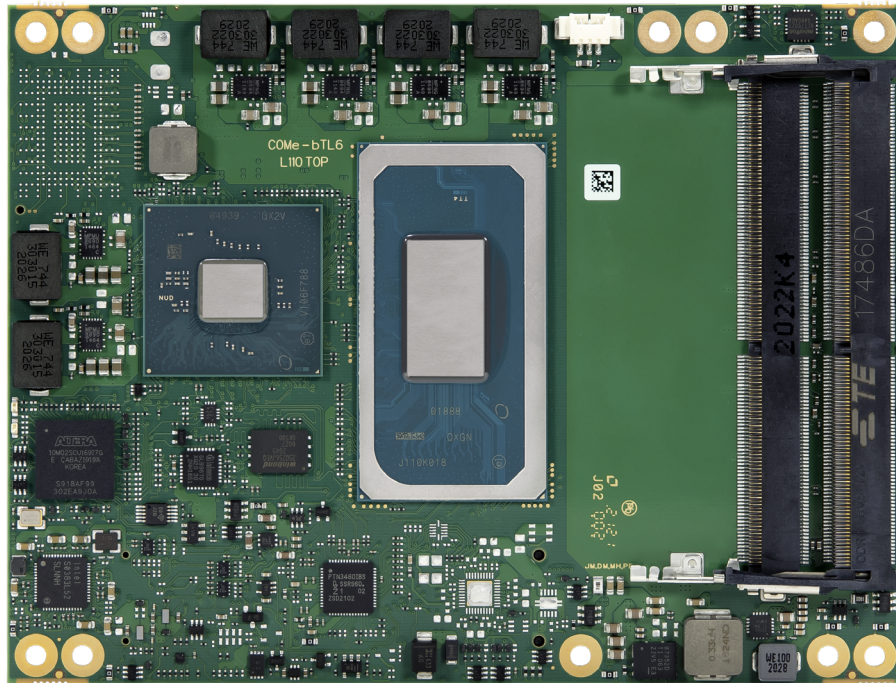


COMe-bTL6 (E2)



COM Express® Basic Type 6 with 11th Generation Intel® Xeon®/ Core™/Celeron® Processors

- ▶ Up to 128 GByte DDR4 memory
- ▶ Up to 2.5 Gb Ethernet with TSN support
- ▶ Optional NVMe SSD onboard
- ▶ Industrial grade versions

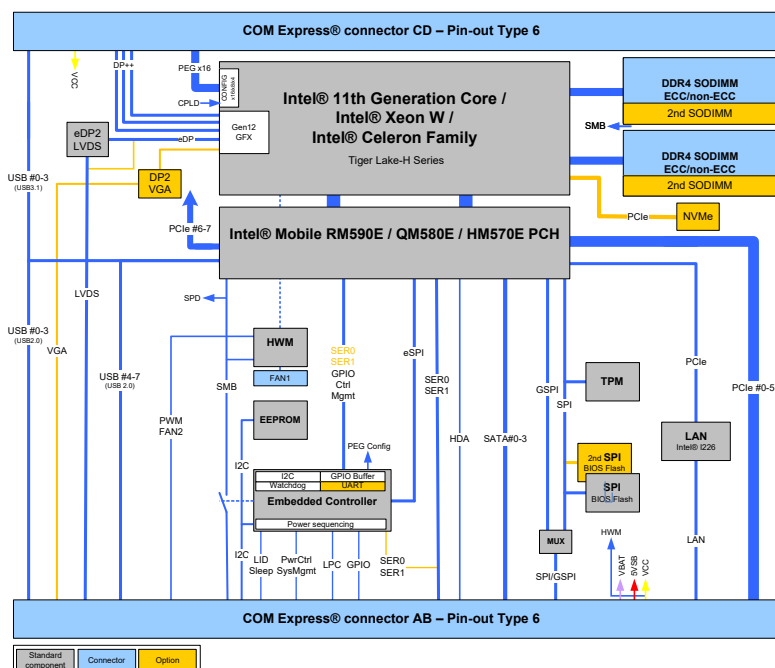


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Technical Information

FEATURES	DESCRIPTION
COMPLIANCE	COM Express® basic, Pin-out Type 6
DIMENSIONS (H X W)	125 x 95 mm
CPU	Intel® 11th Generation Xeon®/Core™/Celeron® family For details see table (CPU variants) given below
CHIPSET	Intel® Mobile RM590E/Intel® Mobile QM580E/Intel® Mobile HM570E
MAIN MEMORY	Up to 4x DDR4-3200 SO-DIMM with up to 128 GByte (non-ECC/ECC) (3rd/4th socket on request)
GRAPHICS CONTROLLER	Intel® UHD Graphics
ETHERNET CONTROLLER	Intel® I225LM/I225IT
ETHERNET	Up to 2.5 Gb Ethernet with TSN support (depending on SKU)
STORAGE	4x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS®	8x PCIe x1, 1x PEG x16
DISPLAY	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	4x USB 3.1 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	Intel® High Definition Audio
OTHER FEATURES	(G)SPI, LPC, SMB, Fast I²C, Staged Watchdog, RTC
SPECIAL FEATURES	POSCAP capacitors, Trusted Platform Module TPM 2.0
FEATURES ON REQUEST	vPRO (AMT/TXT/AES Support), eDP instead of LVDS, VGA, 3rd/4th DDR4 SO-DIMM socket, NVMe SSD, Fail Safe via 2nd SPI Flash
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
BIOS	AMI Aptio V
OPERATING SYSTEM	Windows® 10, Linux, VxWorks
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating Extended temperature: -25 °C to +75 °C operating, -30 °C to +85 °C non-operating Industrial temperature: -40 °C to +85 °C operating, -40 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)

Block Diagram



CPU Variants

11TH GENERATION	CORES	FREQUENCY BASE/ TURBO	TDP	CACHE	TCC/TSN	TEMPERATURE
W-11865MLE	8	1.5/4.5 GHz	25 W	24 MByte	no	commercial
W-11555MLE	6	1.9/4.4 GHz	25 W	12 MByte	no	commercial
W-11155MLE	4	1.8/3.1 GHz	25 W	8 MByte	no	commercial
i7-11850HE	8	2.6/4.7 GHz	45/35 W	24 MByte	no	commercial
i5-11500HE	6	2.6/4.5 GHz	45/35 W	12 MByte	no	commercial
i3-11100HE	4	2.4/4.4 GHz	45/35 W	8 MByte	no	commercial
6600HE	2	2.6 GHz	35 W	8 MByte	no	commercial
W-11865MRE	8	2.6/4.7 GHz	45/35 W	24 MByte	yes	industrial
W-11555MRE	6	2.6/4.5 GHz	45/35 W	12 MByte	yes	industrial
W-11155MRE	4	2.4/4.4 GHz	45/35 W	8 MByte	yes	industrial

Variants

PART NO.	CPU	PCH	MEM. DOWN	SO-DIMM	FLASH	OP. TEMPERATURE
38038-0000-45-8	W-11865MLE	RM590E	-	non-ECC/ECC	-	0 °C - 60 °C
38038-0000-44-6	W-11555MLE	RM590E	-	non-ECC/ECC	-	0 °C - 60 °C
38038-0000-31-4	W-11155MLE	RM590E	-	non-ECC/ECC	-	0 °C - 60 °C
38038-0000-47-7	i7-11850HE	QM580E	-	non-ECC	-	0 °C - 60 °C
38038-0000-46-5	i5-11500HE	QM580E	-	non-ECC	-	0 °C - 60 °C
38038-0000-44-4	i3-11100HE	RM590E	-	non-ECC	-	0 °C - 60 °C
38038-0000-44-3	i3-11100HE	QM580E	-	non-ECC	-	0 °C - 60 °C
38038-0000-26-2	6600HE	HM570E	-	non-ECC	-	0 °C - 60 °C
38039-0000-47-8	W-11865MRE	RM590E	-	non-ECC/ECC	-	-40 °C - 85 °C
38039-0000-46-6	W-11555MRE	RM590E	-	non-ECC/ECC	-	-40 °C - 85 °C
38039-0000-44-4	W-11155MRE	RM590E	-	non-ECC/ECC	-	-40 °C - 85 °C

Carrier

ARTICLE	PART NO.	DESCRIPTION
COMe EVAL CARRIER2 T6	38116-0000-00-5	COM Express® Evaluation Carrier Type 6

Cooling

ARTICLE	PART NO.	DESCRIPTION
HSP COME-BTL6 CU-CORE THREADED	38038-0000-99-0	Heatspreader for COMe-bTL6, Cu-core, threaded mounting holes
HSP COME-BTL6 CU-CORE THROUGH	38038-0000-99-1	Heatspreader for COMe-bTL6, Cu-core, through mounting holes
HSK COME-BASIC ACTIVE (W/O HSP)	38025-0000-99-0C05	Active Cooler for COMe-bxL6/bDV7 to be mounted on HSP
HSK COME-BASIC PASSIVE (W/O HSP)	38025-0000-99-0C06	Passive Cooler for COMe-bxL6/bDV7 to be mounted on HSP

Memory

PART NO.	MIN. SPEC.	SIZE	ECC	OP. TEMPERATURE
97020-3232-BTL6	DDR4-3200	32 GByte	no	0 °C to +60 °C
97020-1632-BTL6	DDR4-3200	16 GByte	no	0 °C to +60 °C
97020-0832-BTL6	DDR4-3200	8 GByte	no	0 °C to +60 °C
97020-0432-BTL6	DDR4-3200	4 GByte	no	0 °C to +60 °C
97021-3232-BTL6	DDR4-3200	32 GByte	no	-40 °C to +85 °C
97021-1632-BTL6	DDR4-3200	16 GByte	no	-40 °C to +85 °C
97021-0832-BTL6	DDR4-3200	8 GByte	no	-40 °C to +85 °C
97021-0432-BTL6	DDR4-3200	4 GByte	no	-40 °C to +85 °C
97030-3232-BTL6	DDR4-3200	32 GByte	yes	0 °C to +60 °C
97030-1632-BTL6	DDR4-3200	16 GByte	yes	0 °C to +60 °C
97030-0832-BTL6	DDR4-3200	8 GByte	yes	0 °C to +60 °C
97030-0432-BTL6	DDR4-3200	4 GByte	yes	0 °C to +60 °C
97031-3232-BTL6	DDR4-3200	32 GByte	yes	-40 °C to +85 °C
97031-1632-BTL6	DDR4-3200	16 GByte	yes	-40 °C to +85 °C
97031-0832-BTL6	DDR4-3200	8 GByte	yes	-40 °C to +85 °C
97031-0432-BTL6	DDR4-3200	4 GByte	yes	-40 °C to +85 °C

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